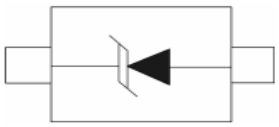
& d h Z ^

— 2000 Watts peak pulse power per line (t_P=8/20μs)
— Solid-state silicon-avalanche technology
— Protects one uni-directional I/O line
— Low clamping voltage
— Working voltage:7V
— Low leakage current
— High surge capability
— RoHS compliant
— AEC-Q101 qualified

SOD-323



Pin Configuration

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— Cell phone handsets and accessories
— Microprocessor based equipment
— Personal digital assistants (PDA's)
— Notebooks, desktops, and servers
— Portable instrumentation
— Power lines
— Peripherals

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— IEC61000-4-2 (ESD) ±30kV (air), ±30kV (contact)
— IEC61000-4-4 (EFT) 40A (5/50ns)
— IEC61000-4-5 (Lightning) 100A (8/20μs)

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— SOD-323 package
— Molding compound flammability rating : UL 94V-0
— Quantity per reel : 3,000pcs
— Lead finish : lead free
— Marking code : 7H

^ K > h d D y / D h D Z d / E h A (TA=25°C, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse power dissipation at 8/20μs waveform	P_{PP}	2000	W
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V_{ESD}	+/- 30 +/- 30	kV
Lead soldering temperature	T_L	260 (10 sec.)	
Operating junction temperature range	T_J		

FIG.3: Pulse derating curve

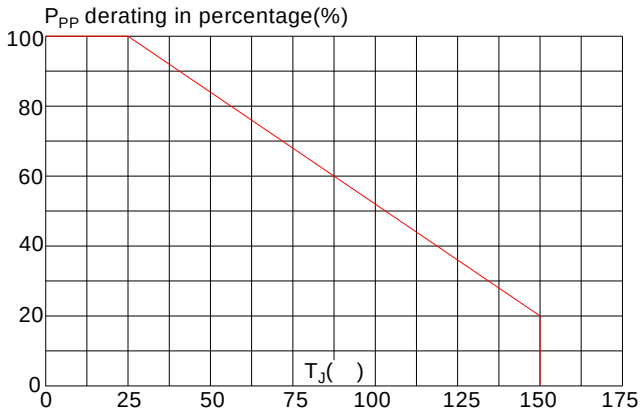
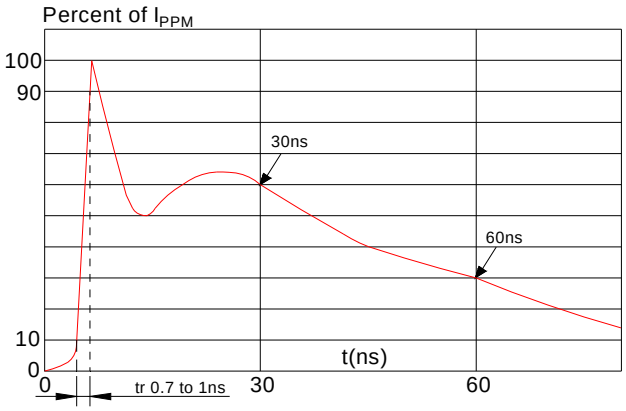
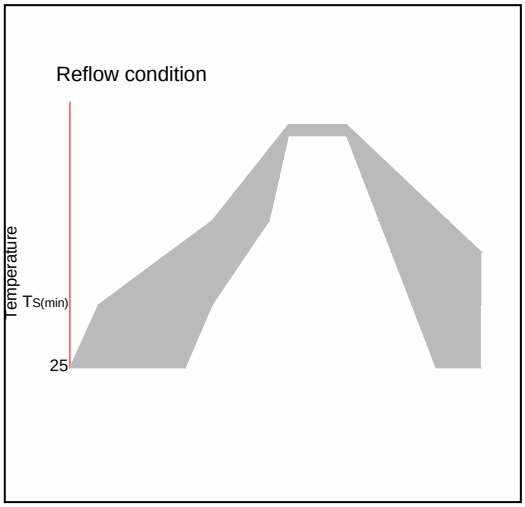


FIG.4: ESD clamping (30kV contact)



^K> Z/E' W Z D d Z^

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150
	-Temperature Max($T_{s(max)}$)	+200
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L)to peak)		3 /sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 /sec. Max
Reflow	-Temperature(T_L)(Liquidus)	+217
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)
Time within 5 of actual Peak Temp (t_p)		20-40secs.
Ramp-down Rate		6 /sec. Max
Time 25 to Peak Temp (T_P)		8 min. Max
Do not exceed		+260



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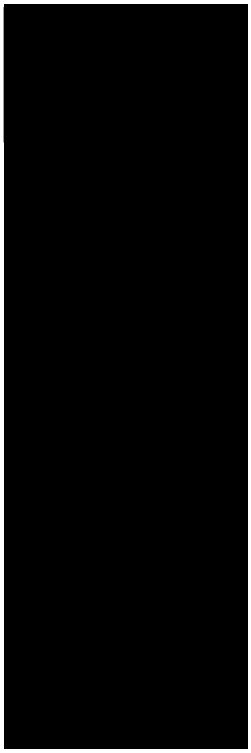

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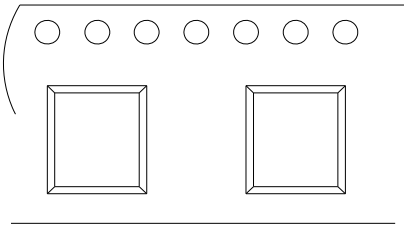

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Part Number	Marking Code